

IN THE CLAIMS

1. (AMENDED) A method of making a semiconductor chip assembly comprising the steps of:

(a) providing a dielectric element having top and bottom surfaces and terminals on said bottom surface;

(b) supporting semiconductor chip having a front surface with contacts thereon, a rear surface and edges extending between said front and rear surfaces above said top surface of said dielectric element by means of a plurality of posts extending between said rear surface of the chip and the top surface of the dielectric element; then

(c) applying a first curable liquid so that said first liquid penetrates between said rear surface and said top surface and penetrates between said posts wherein said step of applying said first liquid includes the steps of placing said first liquid on said top surface of said dielectric element at edges of said chip and applying a gas under pressure around the chip and dielectric element to thereby force said first liquid into the spaces between said posts; then

(d) curing said first liquid to form a flexible rear encapsulant;

(e) connecting said contacts to said terminals by connecting flexible leads between said contacts on said front surface and electrically conductive elements on said dielectric element; and

(f) providing a flexible lead encapsulant around said chip and said flexible leads.

5. (AMENDED) A method as claimed in claim 1 wherein said application of pressure around the chip and dielectric element is a gas under pressure.